# Circuit Description:

The circuit mainly consists of two major components, including main board and Ringslic module. Please see the follow descriptions:

1. Main Board

The main board consists of GSM module (SIM COM: SIM900), power devices (BM1430; LM317), CPU (SST 89V58D2), DTMF detecting devices (UT88L70),which crystal frequency is 3.579MHz,telephone port, power indicator (red LED) and signal Indicator (yellow LED). GSM module is for sending and receiving signal. Power devices are for voltage regulation and depressurizing. DTMF detecting device is for the dialing level identification. CPU is for central processing. Telephone port is for connection with telephone.

2. Ringslic module

Ringslic module (SW0822) has the DC/DC voltage boosting function, ring current generating function, and provision of the 48V external power to telephone.

3. GSM RF module

to achieve the voice,data communications(fax business) wireless access,provides the serial interface and CPU to link and data communications,voice interface and voice channel switching circuit connected and voice communications,with the SIM card interface. GSM RF module is a quad band module which supports GSM/GPRS. The baseband circuit is based on MTK(original ADI part) and RF circuit is based on Renensas. It works at quad bands, GSM850, EGSM900, DCS1800, and PCS1900 band. CPU clock is based on 26MHz crystal. The main IC include AD6720, AD6548, RPF08155B, HWXR874 and Combo Flash, etc.